Atty. Docket No. 29936/39889 Inventor: Sang Kyun Park

Title: Method of Forming Copper Wiring in

Semiconductor Device

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FIG. 1 (PRIOR ART)

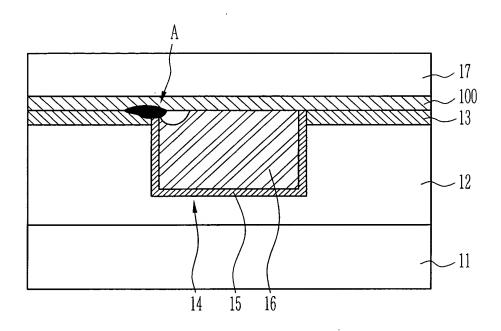
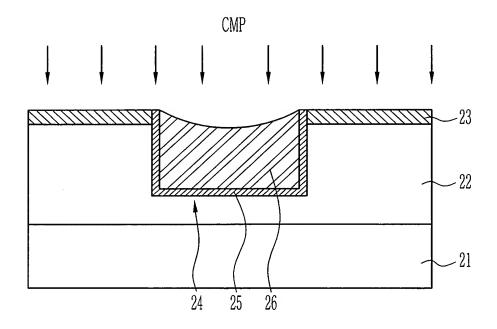


FIG. 2A

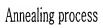


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FIG. 2B



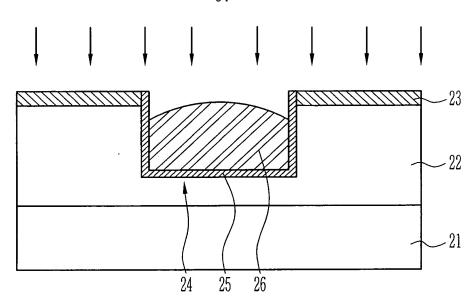
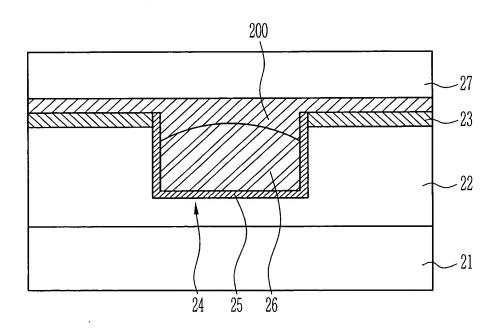


FIG. 2C



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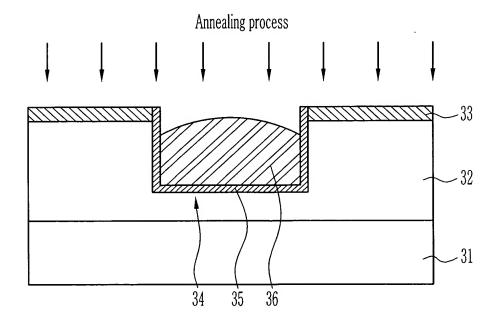
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FIG. 3A CMP - 32 35 36 34

FIG. 3B



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FIG. 3C

